# 2SC4562

### Silicon NPN epitaxial planer type

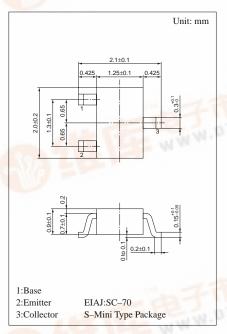
For high-frequency amplification Complementary to 2SA1748

#### Features

- High transition frequency f<sub>T</sub>.
- Small collector output capacitance C<sub>ob</sub>.
- S-Mini type package, allowing downsizing of the equipment and automatic insertion through the tape packing and the magazine packing.

#### Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Ratings	Unit			
Collector to base voltage	$V_{CBO}$	50	V			
Collector to emitter voltage	$V_{CEO}$	50	V			
Emitter to base voltage	$V_{EBO}$	5	V			
Collector current	$I_{C}$	50	mA			
Collector power dissipation	$P_{C}$	150	mW			
Junction temperature	$T_j$	150	°C			
Storage temperature	$T_{stg}$	<b>−55 ~ +150</b>	°C			
	100	-1A	J. COM			
<b>-</b>		E 02				
Electrical Characteristics (Ta=25°C)						



Marking symbol: AM

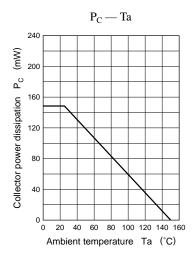
#### Electrical Characteristics (Ta=25°C)

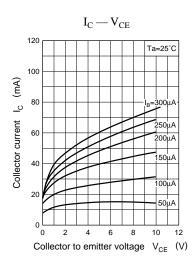
Parameter	Symbol	Conditions	min	typ	max	Unit
C. 11	I <sub>CBO</sub>	$V_{CB} = 10V, I_{E} = 0$			0.1	μΑ
Collector cutoff current	I <sub>CEO</sub>	$V_{CE} = 10V, I_B = 0$			100	μΑ
Collector to base voltage	V <sub>CBO</sub>	$I_{\rm C} = 10 \mu A, I_{\rm E} = 0$	50	-	5 FE	V
Collector to emitter voltage	V <sub>CEO</sub>	$I_C = 1 \text{mA}, I_B = 0$	50	- 1/2	E 46	V
Emitter to base voltage	V <sub>EBO</sub>	$I_{\rm E} = 10 \mu A, I_{\rm C} = 0$	5	L F		V
Forward current transfer ratio	h <sub>FE</sub> *	$V_{CE} = 10V, I_C = 2mA$	200		500	
Collector to emitter saturation voltage	V <sub>CE(sat)</sub>	$I_{C} = 10\text{mA}, I_{B} = 1\text{mA}$		0.06	0.3	V
Transition frequency	$f_T$	$V_{CB} = 10V, I_E = -2mA, f = 200MHz$		250		MHz
Collector output capacitance	C <sub>ob</sub>	$V_{CB} = 10V, I_E = 0, f = 1MHz$		1.5		pF

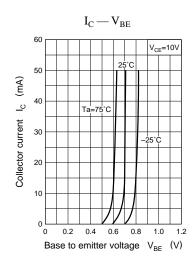
#### \*hFE Rank classification

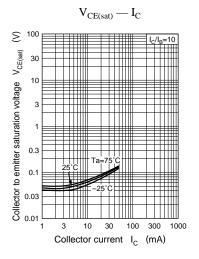
Rank		Q	R	
+#	$h_{ m FE}$	200 ~ 400	250 ~ 500	
Mari	ting Symbol	AMQ	AMR	

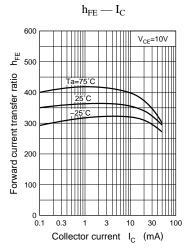
Transistor 2SC4562

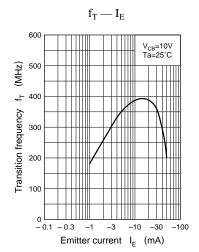


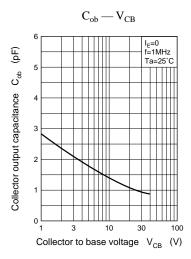












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